

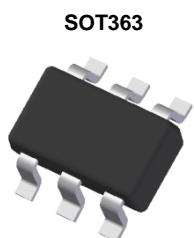
**NPN PRE-BIASED SMALL SIGNAL DUAL SURFACE MOUNT TRANSISTOR**
**Features**

- Epitaxial Planar Die Construction
- Built-In Biasing Resistors
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

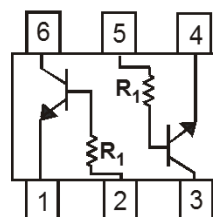
<b>R1 (NOM)</b>
1kΩ

**Mechanical Data**

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.006 grams (Approximate)



Top View

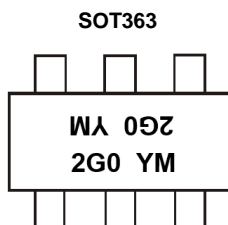


Device Schematic

**Ordering Information** (Note 5)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
ADC113TUQ-7	Automotive	2G0	7	8	3,000
ADC113TUQ-13	Automotive	2G0	13	8	10,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to <https://www.diodes.com/quality/>.
  5. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

**Marking Information**


2G0 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: F = 2018)  
 M = Month (ex: 9 = September)

## Date Code Key

Year	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028
Code	F	G	H	I	J	K	L	M	N	O	P

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

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**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)
 

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Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	50	V
Collector-Emitter Voltage	V <sub>CEO</sub>	50	V
Emitter-Base Voltage	V <sub>EBO</sub>	5	V
Collector Current	I <sub>C</sub> (Max)	100	mA

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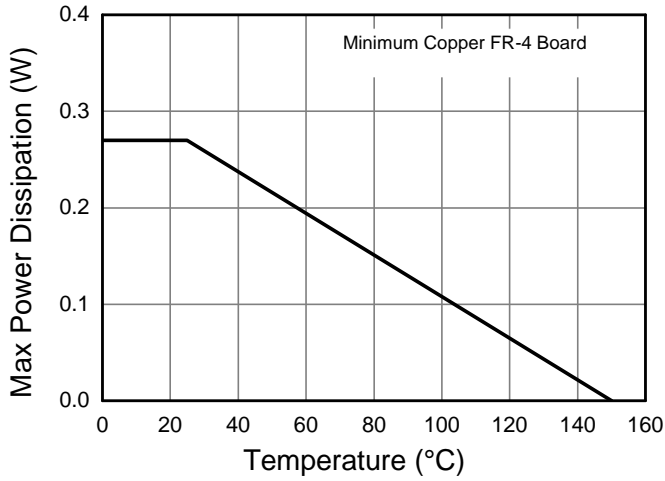
**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)
 

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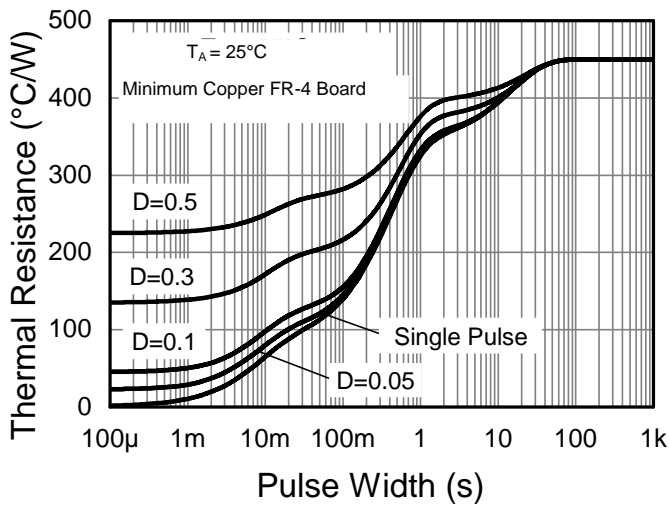
Characteristic	Symbol	Value	Unit
Power Dissipation (Notes 6 & 7)	P <sub>D</sub>	270	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	R <sub>θJA</sub>	450	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes: 6. Mounted on FR-4 PC Board with minimum recommended pad layout.  
 7. 150mW per element must not be exceeded.

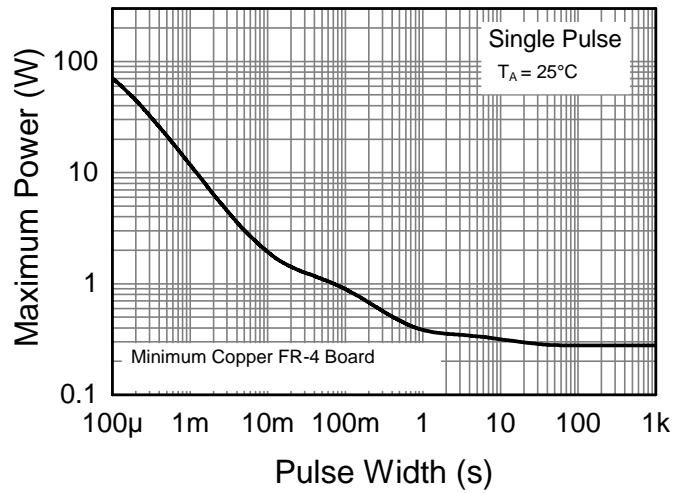
**Thermal Characteristics and Derating Information**



**Derating Curve**



**Transient Thermal Impedance**



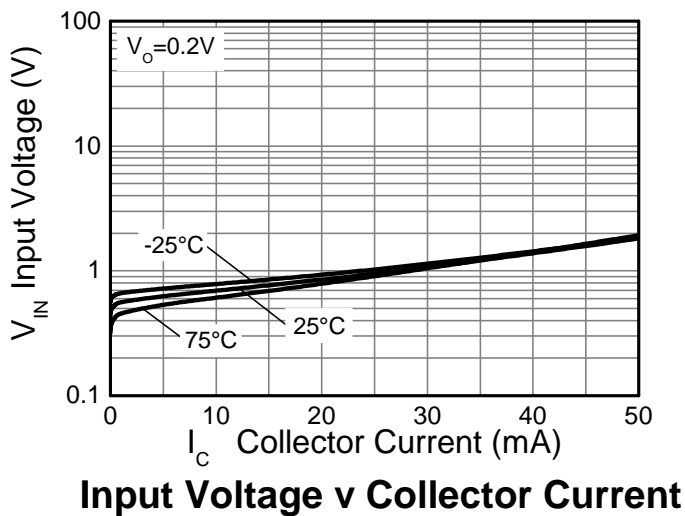
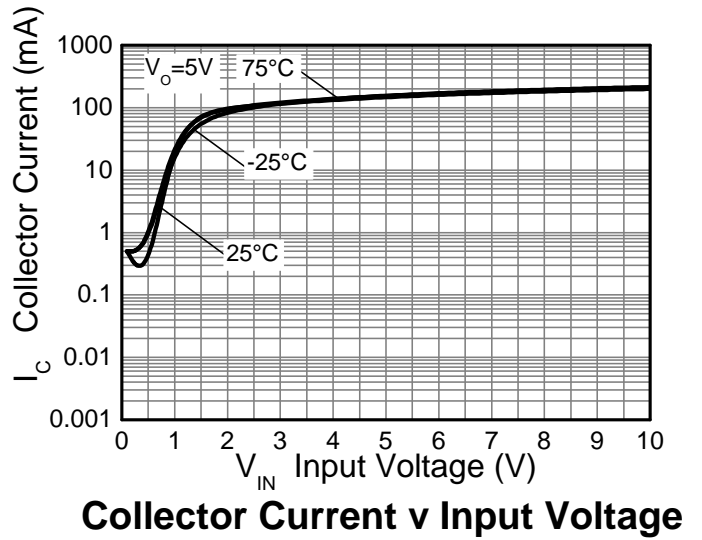
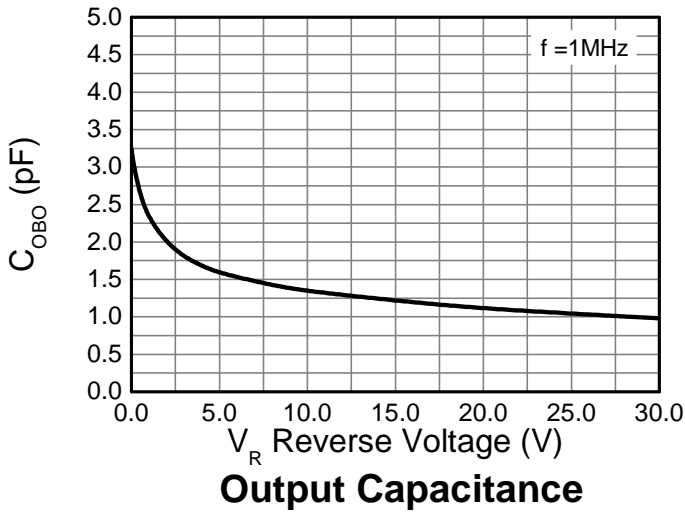
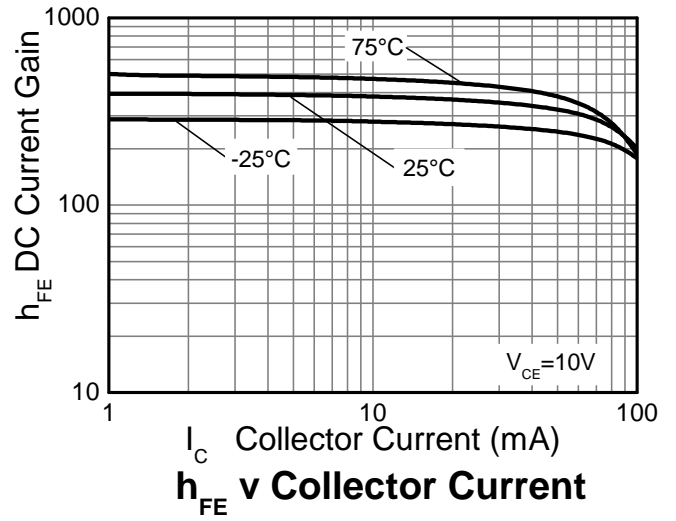
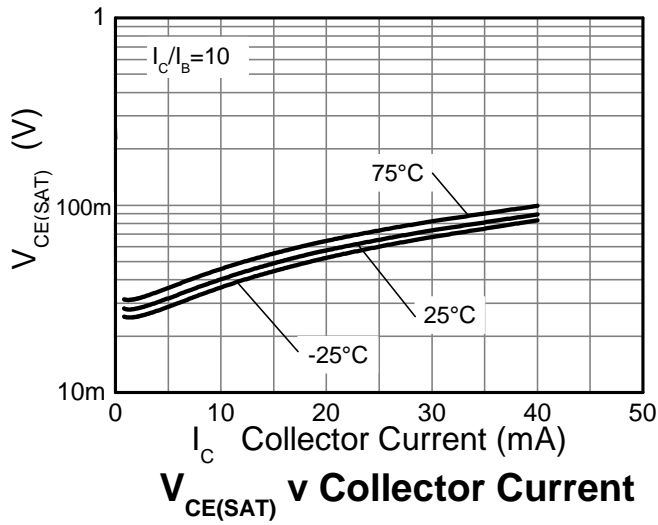
**Pulse Power Dissipation**

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	50	—	—	V	I <sub>C</sub> = 50μA
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	50	—	—	V	I <sub>C</sub> = 1mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	5	—	—	V	I <sub>E</sub> = 50μA
Collector Cutoff Current	I <sub>CBO</sub>	—	—	0.5	μA	V <sub>CB</sub> = 50V
Emitter Cutoff Current	I <sub>EBO</sub>	—	—	0.5	μA	V <sub>EB</sub> = 4V
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	—	—	0.3	V	I <sub>C</sub> /I <sub>B</sub> = 10mA/1mA
DC Current Transfer Ratio	h <sub>FE</sub>	100	250	600	—	I <sub>C</sub> = 1mA, V <sub>CE</sub> = 5V
Input Resistor (R <sub>1</sub> ) Tolerance	ΔR <sub>1</sub>	-30	—	+30	%	—
Gain-Bandwidth Product (Note 8)	f <sub>T</sub>	—	250	—	MHz	V <sub>CE</sub> = 10V, I <sub>E</sub> = -5mA, f = 100MHz

Note: 8. Transistor - For Reference Only.

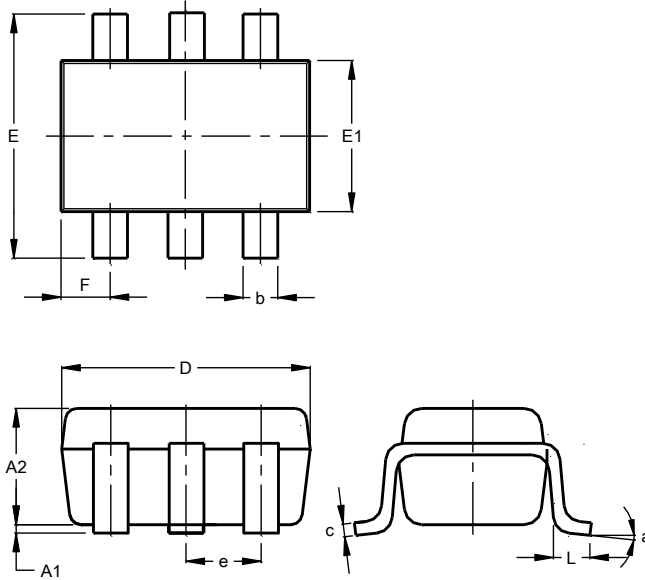
**Typical Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)



**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT363**

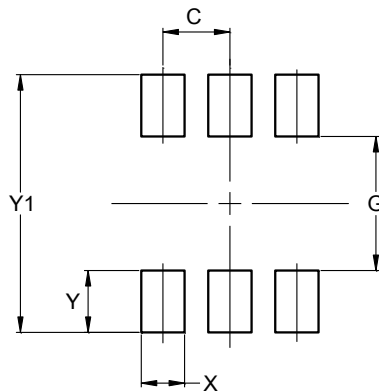


SOT363			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT363**



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500

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